Mill-Max Introduces Super Low-Profile Sockets

Reliable and compact sockets for minimizing interconnect height

Mill-Max is proud to present its lowest profile strip sockets to date. With an above-board height of just .083” (2.11 mm) these sockets provide a reliable and convenient way to connect boards or devices.

Many of today’s products, such as implantable and wearable devices for the medical industry, demand miniaturization along with high functionality and reliability. Those requirements drive designers to find durable solutions to package more electronics into smaller spaces; these new sockets can be exactly what they are looking for.

The new 315-43-1XX-41-004000 (single row) and 415-43-2XX-41-004000 (double row) sockets have .100” (2.54 mm) pin spacing with a low profile of .083” (2.11 mm). They are designed for through hole mounting in boards up to .062” (1.57 mm) thick, providing a secure connection to the PCB. These sockets are ideal for board stacking and wire to board applications where minimizing package height is paramount. When mated with Mill-Max low profile headers, 335-10-1XX-00-160000 (single row) and 435-10-2XX-00-160000 (double row), the total between the boards height is only .155” (3.94 mm). For wire to board connections the Mill-Max 380-10-1XX-00-002000 (Single row) and 480-10-2XX-00-002000 (Double row) solder cup headers combine with the super low-profile sockets to achieve a total height of .268” (6.81 mm).

Each receptacle is precision turned from brass alloy, has a highly reliable 4 finger, beryllium copper contact, accepts leads ranging from .015” - .022” (.38 - .56 mm) and is designed to withstand the rigors of rugged applications associated with portability. The insulator material is high temperature PCT, compatible with most soldering processes. Connectors are available from 1-32 positions, single row and 4 -72 positions double row. Standard plating options include tin or gold for the outer shell and gold for the internal contact providing optimal interconnect reliability.

For more information, please visit www.mill-max.com/PR685.
SERIES 315 & 415 • .100” GRID, SUPER LOW PROFILE SOCKETS • SINGLE AND DOUBLE ROW STRIPS

- Series 315 and 415 solder mount sockets use MM #0512 receptacles that accept pin diameters from .015”-.022”. See pages 161 for details.
- Hi-Rel, 4-finger BeCu #12 contact is rated at 3 amps. See page 252 for details.
- .083” Super low profile above the board utilizes .050” thick insulators.
- Insulators are high temperature thermoplastic, suitable for all soldering operations.

ORDERING INFORMATION

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<tr>
<th>FIG. 1</th>
<th>Series 315...004 Single Row Socket</th>
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<tr>
<td>315-XX-1_ _-41-004000 Specify number of pins 01-32</td>
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<th>FIG. 2</th>
<th>Series 415...004 Double Row Socket</th>
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<tr>
<td>415-XX-2_ _-41-004000 Specify number of pins 04-72</td>
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RoHS-2 2011/65/EU

XX=Plating Code See Below

SPECIFY PLATING CODE XX=

- Sleeve (Pin)  
  - 10 μ“ Au
  - 200 μ“Sn/Pb
  - 200 μ“Sn
  - 200 μ“Sn
- Contact (Clip)  
  - 30 μ“Au
  - 30 μ“Au
  - 30 μ“Au
  - 100 μ“Sn
  - Au Flash

For Electrical, Mechanical & Environmental Data, See page 264